

TO-220AB Plastic-Encapsulate MOSFETs

IRF840 MOSFET(N-Channel)

FEATURES

- Dynamic dv/dt Rating
- Repetitive Avalanche Rated
- Fast Switching
- Ease of Parallelizing
- Simple Drive Requirement

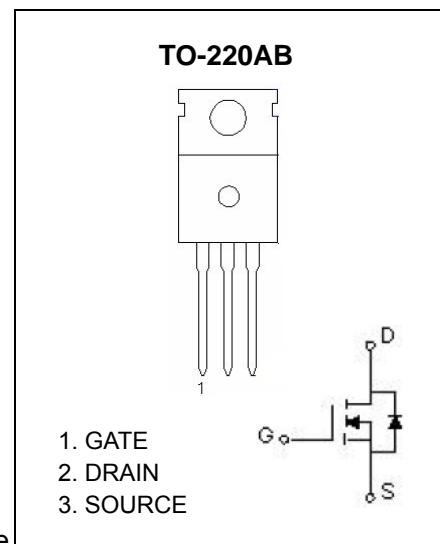
Description

Third Generation HEXFETs from International Rectifier provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost effectiveness.

The TO-220 package is universally preferred for all commercial-industrial applications. The low thermal resistance and low package cost of the TO-220 contribute to its wide acceptance throughout the industry.

MAXIMUM RATINGS($T_a=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Value	Units
I_D	Continuous Drain Current, $V_{GS} @ 10 \text{ V}$	8	A
	$T_c=25^\circ\text{C}$	5.1	A
I_{DM}	Pulsed Drain Current (note 1)	32	A
P_D	Power Dissipation	2	W
V_{GS}	Gate-Source Voltage	± 20	V
E_{AS}	Single Pulse Avalanche Energy (note 2)	510	mJ
I_{AR}	Avalanche Current (note 1)	8	A
E_{AR}	Repetitive Avalanche Energy (note 1)	13	mJ
dv/dt	Peak Diode Recovery dv/dt (note 3)	3.5	V/ns
$R_{\theta JA}$	Thermal Resistance from Junction to Ambient	62.5	$^\circ\text{C}/\text{W}$
T_J	Junction Temperature	150	$^\circ\text{C}$
T_{STG}	Storage Temperature	-55~+150	$^\circ\text{C}$



ELECTRICAL CHARACTERISTICS ($T_a=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
Drain-source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	500			V
Gate-threshold voltage	$V_{\text{th}(\text{GS})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	2		4	
Gate-body leakage	I_{GSS}	$V_{\text{DS}}=0\text{V}, V_{\text{GS}}=\pm 20\text{V}$			± 100	nA
Zero gate voltage drain current	I_{DSS}	$V_{\text{DS}}=500\text{V}, V_{\text{GS}}=0\text{V}$			25	μA
Drain-source on-resistance	$R_{\text{DS}(\text{On})}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=4.8\text{A}$			0.85	Ω
Forward transconductance	g_{fs}	$V_{\text{DS}}=50\text{V}, I_{\text{D}}=4.8\text{A}$	4.9			S
Diode forward voltage	V_{SD}	$I_{\text{S}}=8\text{A}, V_{\text{GS}}=0\text{V}$			2	V
Total gate charge	Q_g	$V_{\text{DS}}=400\text{V}, V_{\text{GS}}=10\text{V}, I_{\text{D}}=8\text{A}$			63	nC
Gate-source charge	Q_{gs}				9.3	
Gate-drain charge	Q_{gd}				32	
Input capacitance	C_{iss}	$V_{\text{DS}}=25\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$		1300		pF
Output capacitance	C_{oss}			310		
Reverse transfer capacitance	C_{rss}			120		
Turn-on time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=250\text{V}, R_{\text{D}}=31\Omega, I_{\text{D}}=8\text{A}, R_{\text{G}}=9.1\Omega$		14		ns
Rise time	t_r			23		
Turn-off time	$t_{\text{d}(\text{off})}$			49		
Fall time	t_f			20		

Notes:

1. Repetitive Rating ; Pulse width limited by maximum junction temperature
2. $L=14\text{mH}, I_{\text{AS}} = 8.0\text{A}, V_{\text{DD}}=50\text{V}, R_{\text{G}}=25\Omega$, starting $T_J = 25^\circ\text{C}$
3. $I_{\text{SD}} \leq 8.0\text{A}$, $dI/dt \leq 100\text{A}/\mu\text{s}$, $V_{\text{DD}} \leq V_{(\text{BR})\text{DSS}}$, $T_J \leq 150^\circ\text{C}$
4. Pulse width $\leq 300\mu\text{s}$, Duty cycle $\leq 2\%$